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(54) **METHOD FOR CHECKING ENERGIZATION TO
 WAFER AND PLATING JIG AND APPARATUS
 FOR CHECKING ENERGIZATION**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a method for checking the energization of a wafer and plating jig which is capable of extremely easily and surely checking the energization state of the energizing pins of the plating jig and the conductive film of the wafer.

SOLUTION: This method is to check the energization of the energizing pins 12-1 to 4 of the plating jig and the conductive film on the wafer 3 by mounting the wafer 3 on the plating jig including the plural energizing pins 12-1 to 4 to be brought into contact with the conductive film on the wafer 3. The electric resistance between the energizing pins 12-1 to 4 of the plating jig is measured by electric resistance measuring instruments 14-1 to 2 and the electrical contact state of the conductive film on the wafer 3 and the energizing pins 12-1 to 4 is checked with the electric resistance value.

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